NCP4629

500 mA, Wide Input Range, LDO Linear Voltage Regulator

The NCP4629 is a CMOS 500 mA LDO linear voltage regulator which features a high input voltage range while maintaining a low quiescent current. Several protection features like current limiting and thermal shutdown are fully integrated to create a versatile and robust device. A high maximum input voltage (36 V) and wide temperature range (−40°C to 105°C) makes the NCP4629 an ideal choice for high power industrial applications.

Features

- Operating Input Voltage Range: 4 V to 24 V
- Output Voltage Range: 3.0 to 12.0 V (available in 0.1 V steps)
- ±2% Output Voltage Accuracy
- Output Current: min. 500 mA (V_{IN} = V_{OUT} + 1 V)
- Line Regulation: 0.05%/V
- Current Limit Circuit
- Thermal Shutdown Circuit
- Available in SOT−89−5 and DPACK5 Package
- These are Pb−Free Devices

Typical Applications

- Home appliances, industrial equipment
- Cable boxes, satellite receivers, entertainment systems
- Car audio equipment, navigation systems
- Notebook adaptors, LCD TVs, cordless phones and private LAN systems
- Office equipment: copiers, printers, facsimiles, scanners, projectors, monitors

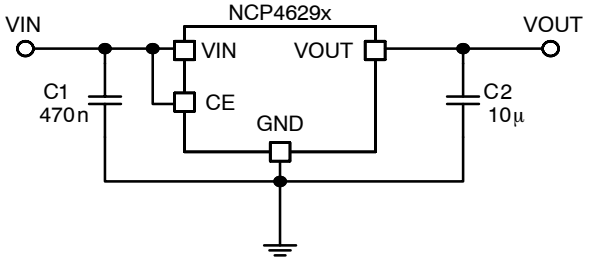

Figure 1. Typical Application Schematic

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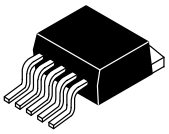
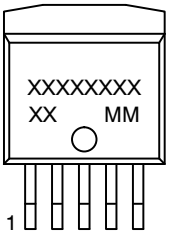
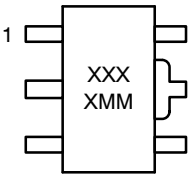
MARKING DIAGRAMS



DPAK−5
CASE 369AE



SOT−89 5
CASE 528AB



XX, XXX = Specific Device Code
M, MM = Date Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

(*Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 13 of this data sheet.

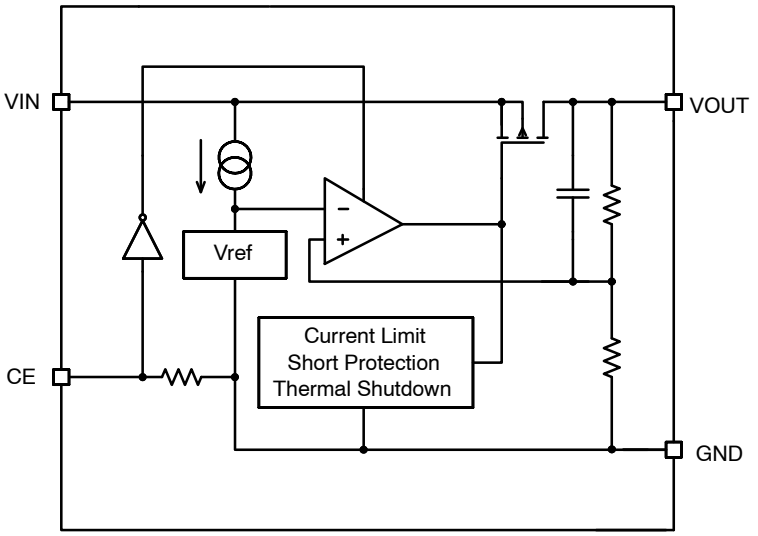


Figure 2. Simplified Schematic Block Diagram

PIN FUNCTION DESCRIPTION

Pin No. SOT89	Pin No. DPACK	Pin Name	Description
1	1	VIN	Input pin
2	2	GND	Ground pin, all ground pins must be connected together when it is mounted on board
3	3	GND	Ground pin, all ground pins must be connected together when it is mounted on board
4	4	CE	Chip enable pin (“H” active)
5	5	VOUT	Output pin

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage	V_{IN}	−0.3 to 36	V
Output Voltage	V_{OUT}	−0.3 to $V_{IN} \le 36$	V
Chip Enable Input	V_{CE}	−0.3 to $V_{IN} \le 36$	V
Power Dissipation SOT−89	P_D	900	mW
Power Dissipation DPACK		1900	
Junction Temperature	T_J	−40 to 150	°C
Storage Temperature	T_{STG}	−55 to 125	°C
ESD Capability, Human Body Model (Note 2)	ESD_{HBM}	2000	V
ESD Capability, Machine Model (Note 2)	ESD_{MM}	200	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Duration time = 200 ms
2. This device series incorporates ESD protection and is tested by the following methods:
   ESD Human Body Model tested per AEC−Q100−002 (EIA/JESD22−A114)
   ESD Machine Model tested per AEC−Q100−003 (EIA/JESD22−A115)
   Latch−up Current Maximum Rating tested per JEDEC standard: JESD78.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Characteristics, SOT−89 Thermal Resistance, Junction−to−Air	$R_{\theta JA}$	111	°C/W
Thermal Characteristics, DPACK Thermal Resistance, Junction−to−Air	$R_{\theta JA}$	53	°C/W

ELECTRICAL CHARACTERISTICS T_A = 25°C

Parameter	Test Conditions		Symbol	Min	Typ	Max	Unit
Operating Input Voltage			V_{IN}	4		24	V
Output Voltage	V_{IN} = V_{OUT} + 1 V, I_{OUT} = 100 mA		V_{OUT}	x0.98		x1.02	V
Output Voltage Temp. Coefficient	V_{IN} = V_{OUT} + 2 V, I_{OUT} = 100 μA, T_A = −40 to 105°C				±100		ppm/°C
Line Regulation	V_{IN} = V_{OUT} + 1 V to 24 V, I_{OUT} = 10 mA		$Line_{Reg}$		0.05	0.10	%/V
Load Regulation	V_{IN} = V_{OUT} + 2 V, I_{OUT} = 0.1 mA to 200 mA		$Load_{Reg}$		25	60	mV
Dropout Voltage	I_{OUT} = 200 mA	3.0 V ≤ V_{OUT} < 5.0 V	V_{DO}		0.135	0.225	V
		5.0 V ≤ V_{OUT} < 9.0 V			0.115	0.180	
		8.0 V ≤ V_{OUT} ≤ 12.0 V			0.095	0.155	
Output Current	V_{IN} = V_{OUT} + 1 V		I_{OUT}	500			mA
Short Current Limit	V_{OUT} = 0 V		I_{SC}		65		mA
Quiescent Current	V_{IN} = V_{OUT} + 1 V, V_{IN} = V_{CE}		I_Q		70	130	μA
Standby Current	V_{IN} = 24 V, V_{CE} = 0 V		I_{STB}		0.1	1	μA
CE Pin Threshold Voltage	CE Input Voltage “H”		V_{CEH}	2.0		V_{IN}	V
	CE Input Voltage “L”		V_{CEL}	0		0.4	
Thermal Shutdown Temperature			T_{SD}		160		°C
Thermal Shutdown Release Temperature			T_{SR}		135		°C
Power Supply Rejection Ratio	V_{IN} = V_{OUT} + 2.0 V, ΔV_{IN_PK-PK} = 0.5 V, I_{OUT} = 100 mA, f = 1 kHz	V_{OUT} ≤ 6.0 V	PSRR		60		dB
		V_{OUT} > 6.0 V			50		
Output Noise Voltage	V_{OUT} = TBD V, I_{OUT} = TBD mA, f = 10 Hz to 100 kHz		V_N		TBD		μV_{rms}

TYPICAL CHARACTERISTICS

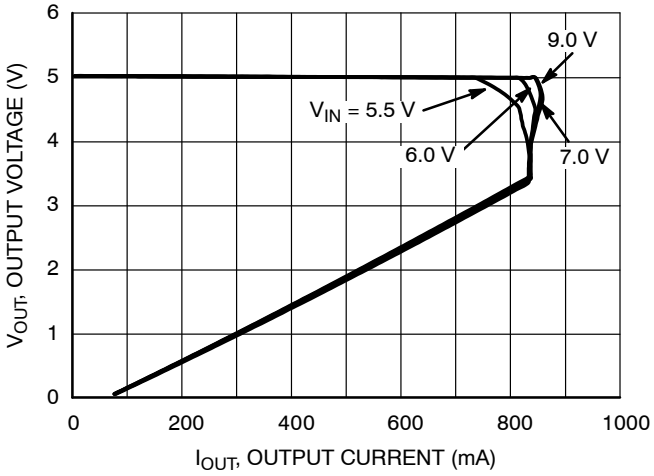


Figure 3. Output Voltage vs. Output Current, V_{OUT} = 5 V

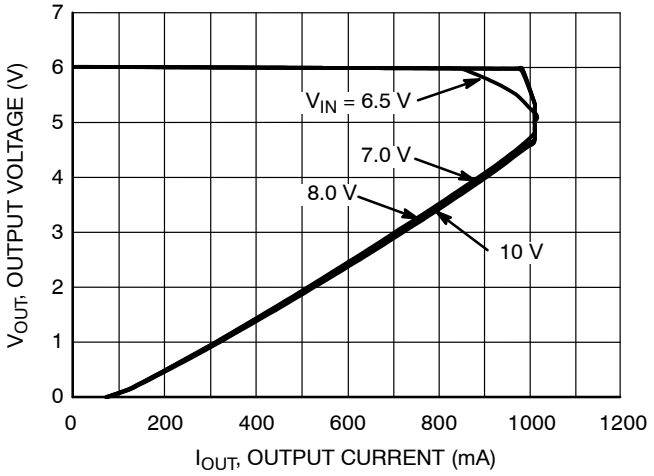


Figure 4. Output Voltage vs. Output Current, V_{OUT} = 6 V

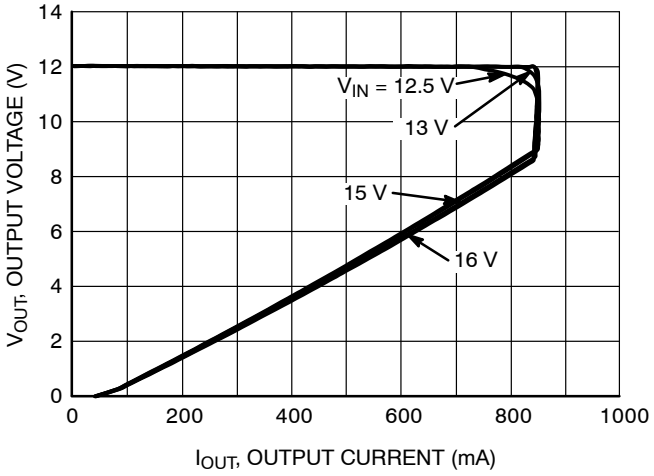


Figure 5. Output Voltage vs. Output Current, V_{OUT} = 12 V

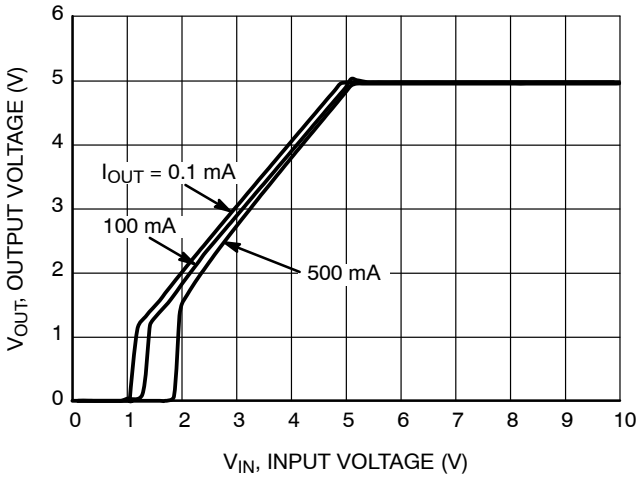


Figure 6. Output Voltage vs. Input Voltage, V_{OUT} = 5 V

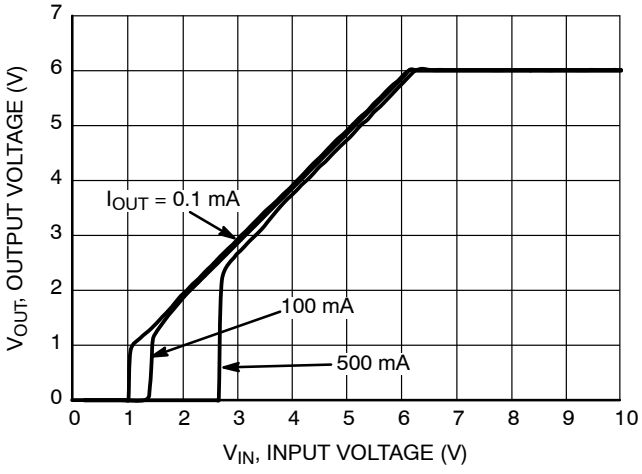


Figure 7. Output Voltage vs. Input Voltage, V_{OUT} = 6 V

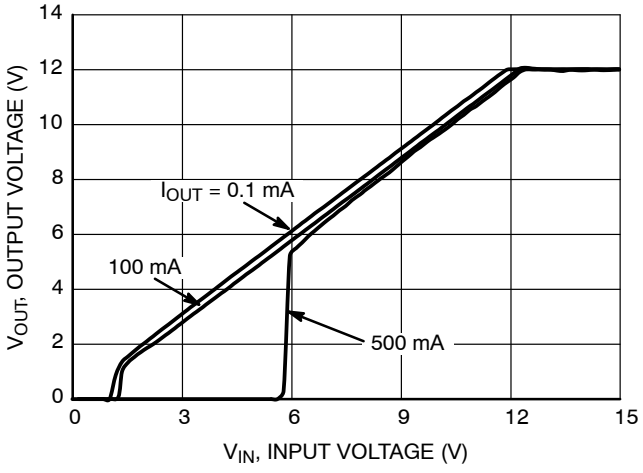


Figure 8. Output Voltage vs. Input Voltage, V_{OUT} = 12 V

TYPICAL CHARACTERISTICS

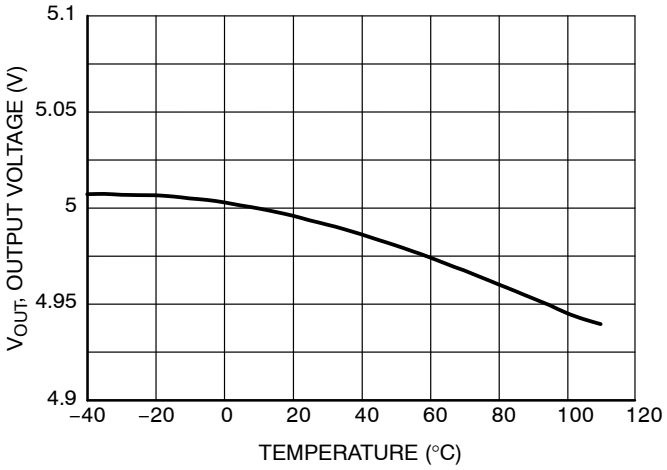


Figure 9. Output Voltage vs. Temperature, V_{OUT} = 5 V

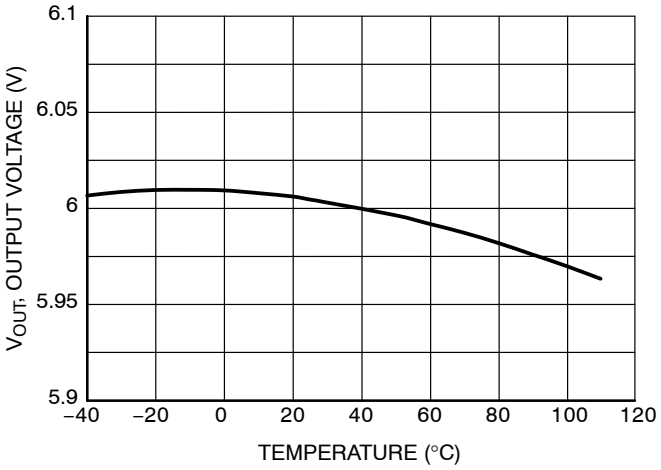


Figure 10. Output Voltage vs. Temperature, V_{OUT} = 6 V

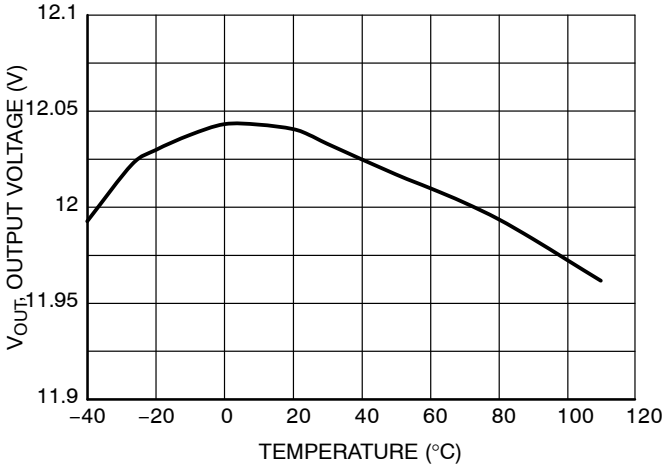


Figure 11. Output Voltage vs. Temperature, V_{OUT} = 12 V

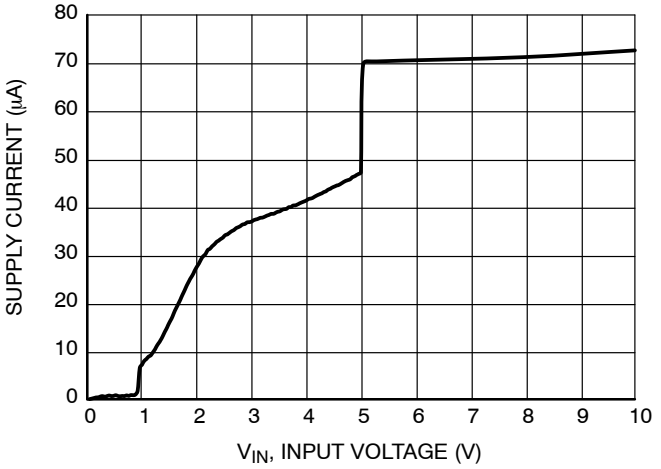


Figure 12. Supply Current vs. Input Voltage, V_{OUT} = 5 V

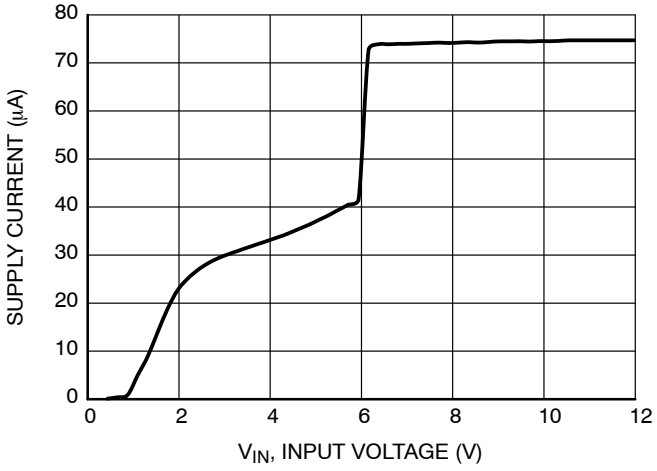


Figure 13. Supply Current vs. Input Voltage, V_{OUT} = 6 V

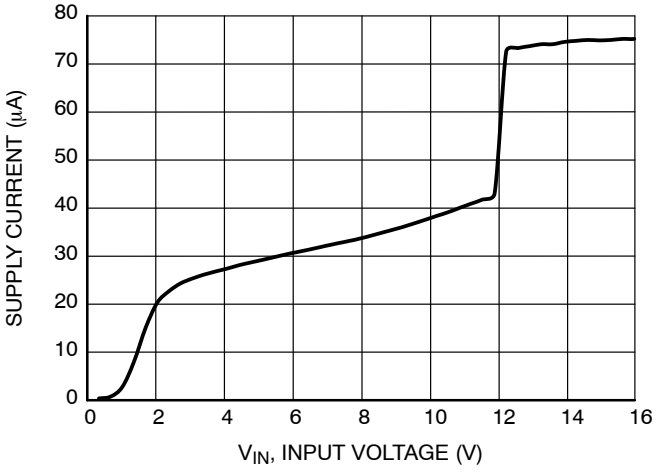


Figure 14. Supply Current vs. Input Voltage, V_{OUT} = 12 V

TYPICAL CHARACTERISTICS

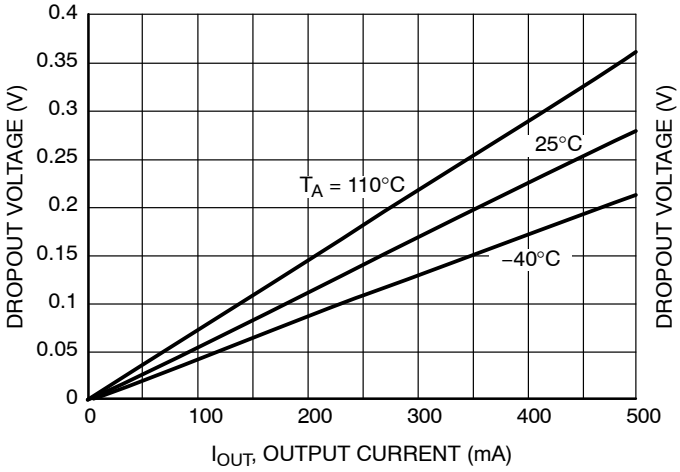


Figure 15. Dropout Voltage vs. Input Current, V_{OUT} = 5 V

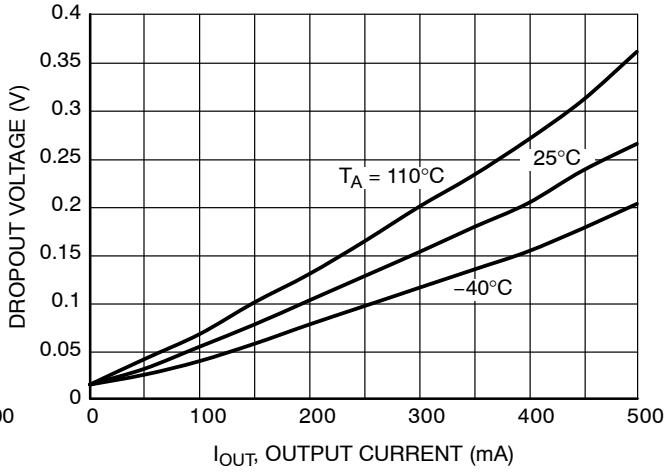


Figure 16. Dropout Voltage vs. Input Current, V_{OUT} = 6 V

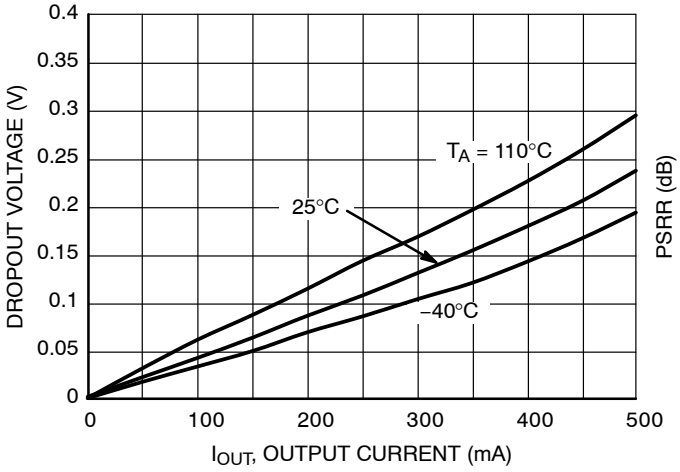


Figure 17. Dropout Voltage vs. Input Current, V_{OUT} = 12 V

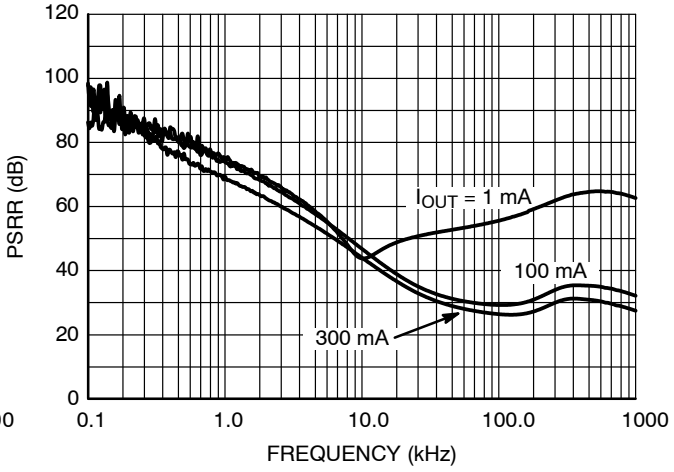


Figure 18. Ripple Rejection vs. Frequency, V_{OUT} = 5 V

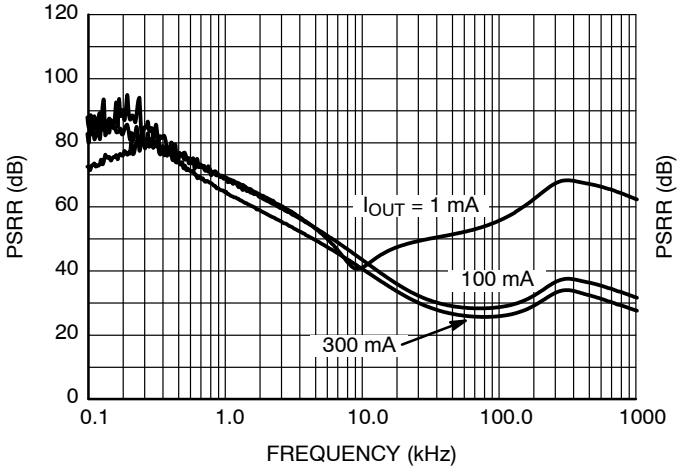


Figure 19. Ripple Rejection vs. Frequency, V_{OUT} = 6 V

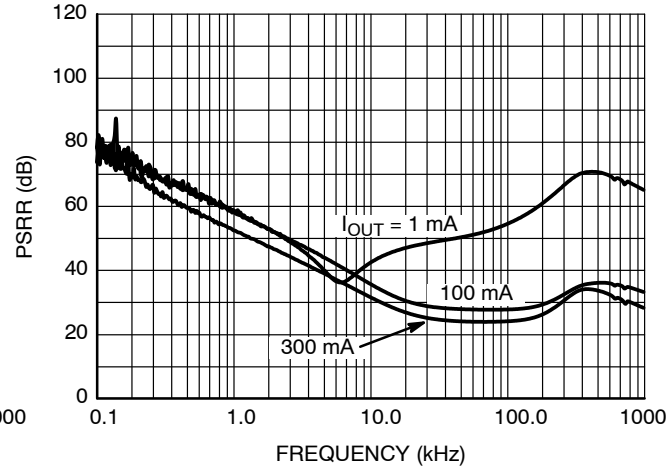


Figure 20. Ripple Rejection vs. Frequency, V_{OUT} = 12 V

TYPICAL CHARACTERISTICS

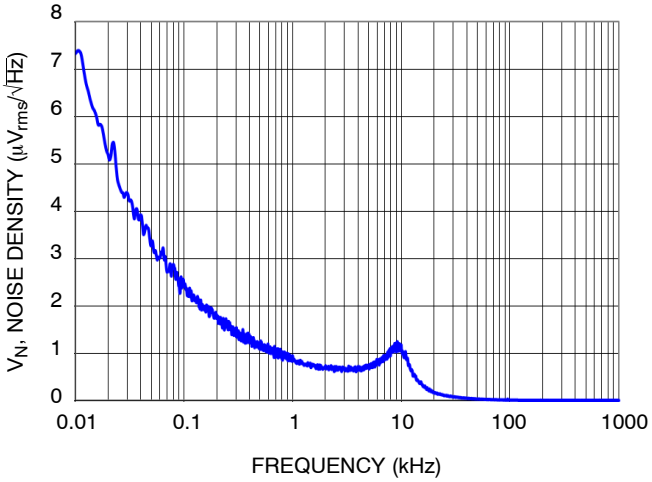


Figure 21. Output Noise Density, V_{OUT} = 5 V

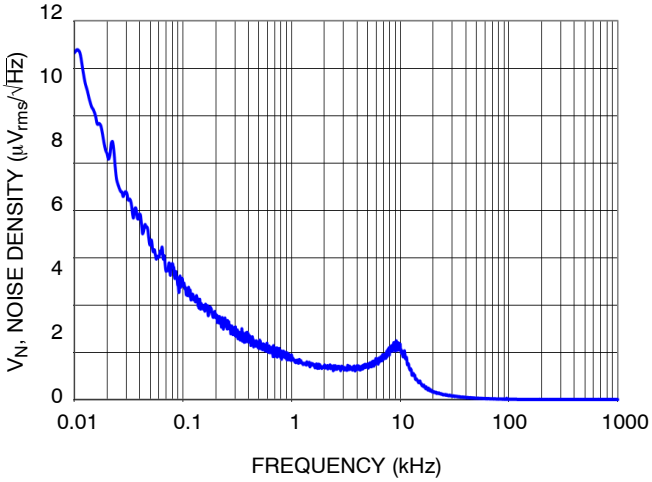


Figure 22. Output Noise Density, V_{OUT} = 6 V

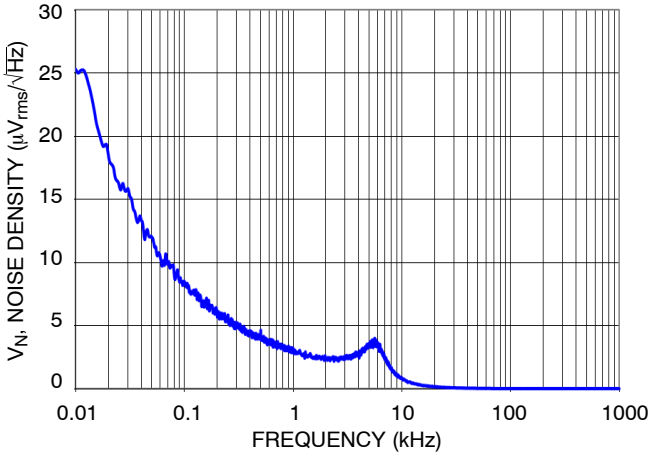


Figure 23. Output Noise Density, V_{OUT} = 12 V

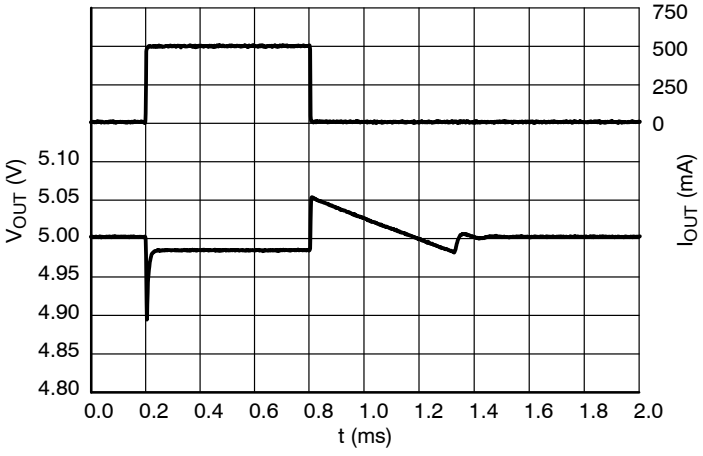


Figure 24. Load Transient Response at Output Current Step 1 mA to 500 mA, V_{OUT} = 5 V

TYPICAL CHARACTERISTICS

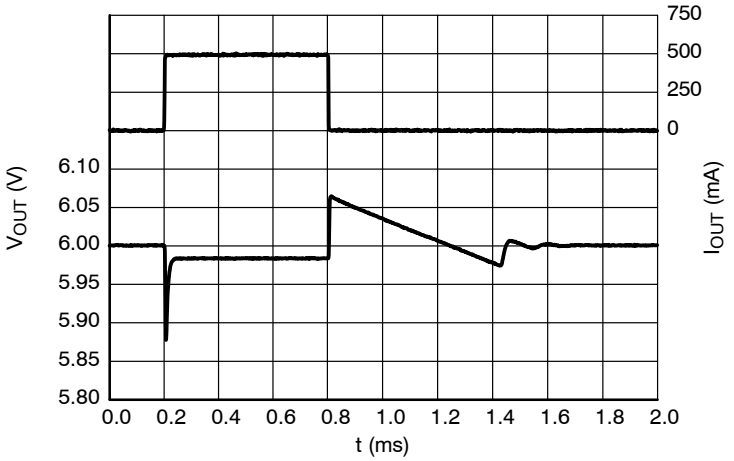


Figure 25. Load Transient Response at Output Current Step 1 mA to 500 mA, V_{OUT} = 6 V

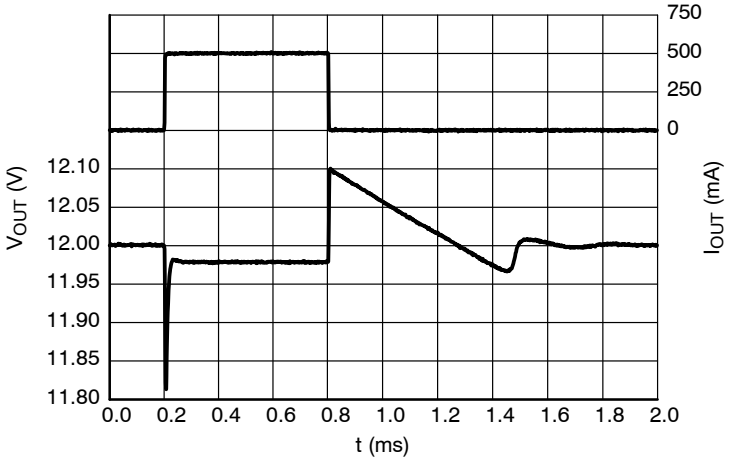


Figure 26. Load Transient Response at Output Current Step 1 mA to 500 mA, V_{OUT} = 12 V

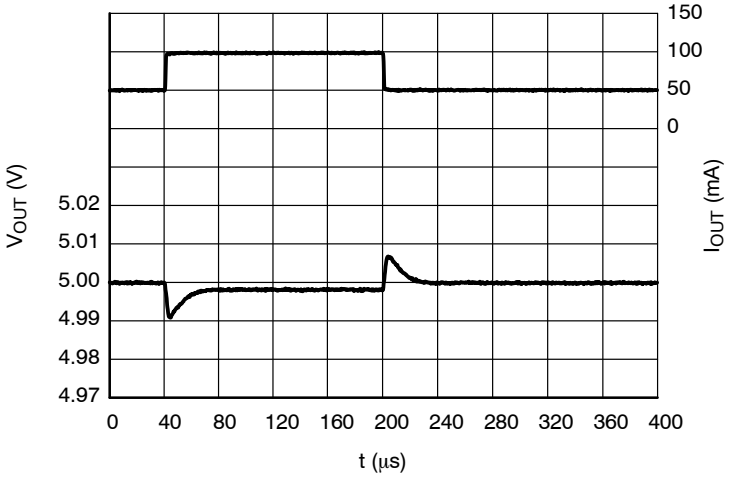


Figure 27. Load Transient Response at Output Current Step 50 mA to 100 mA, V_{OUT} = 5 V

TYPICAL CHARACTERISTICS

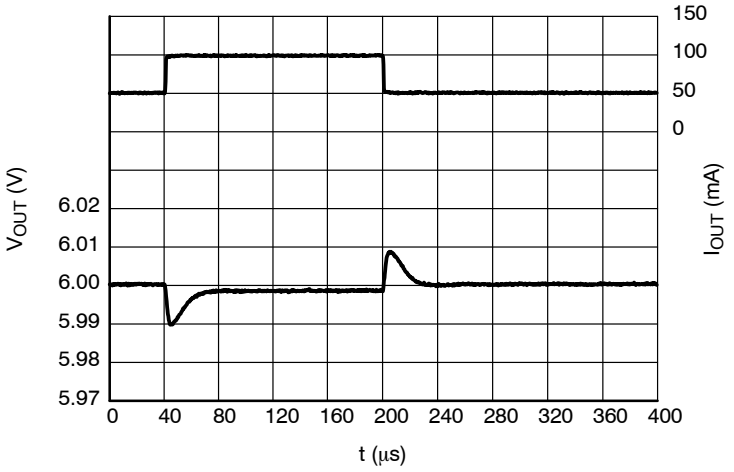


Figure 28. Load Transient Response at Output Current Step 50 mA to 100 mA, V_{OUT} = 6 V

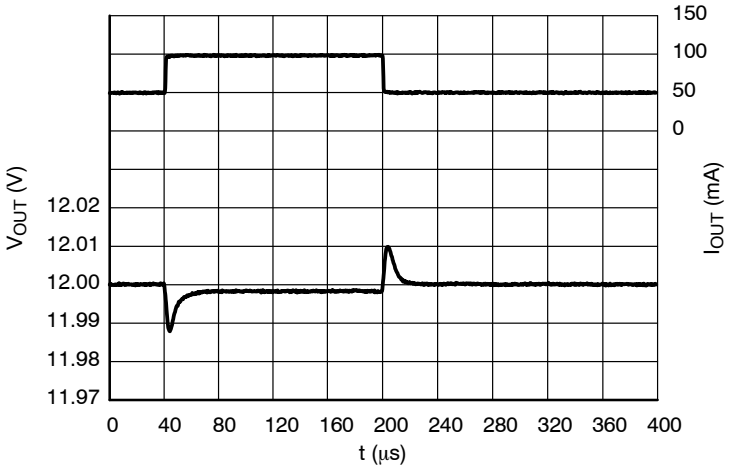


Figure 29. Load Transient Response at Output Current Step 50 mA to 100 mA, V_{OUT} = 12 V

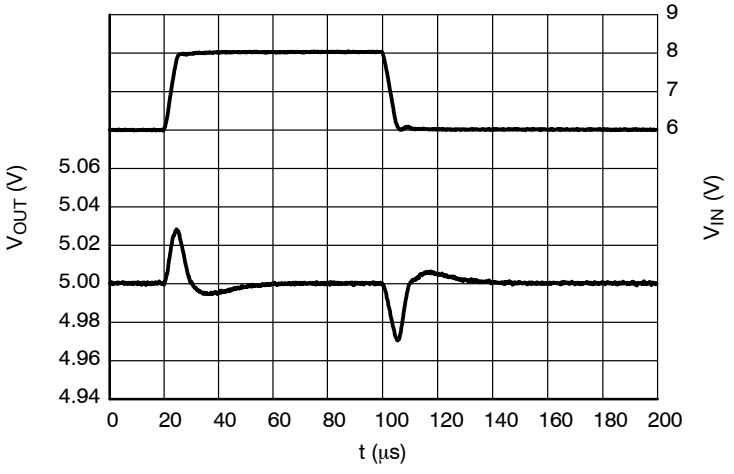


Figure 30. Line Transient Response, V_{OUT} = 5 V

TYPICAL CHARACTERISTICS

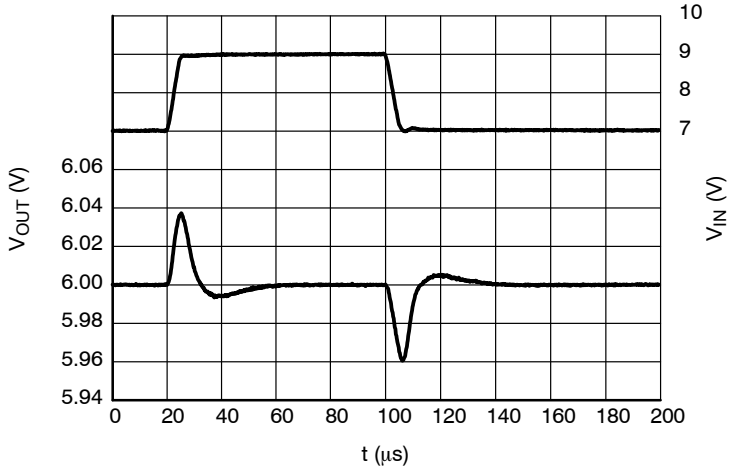


Figure 31. Line Transient Response, V_{OUT} = 6 V

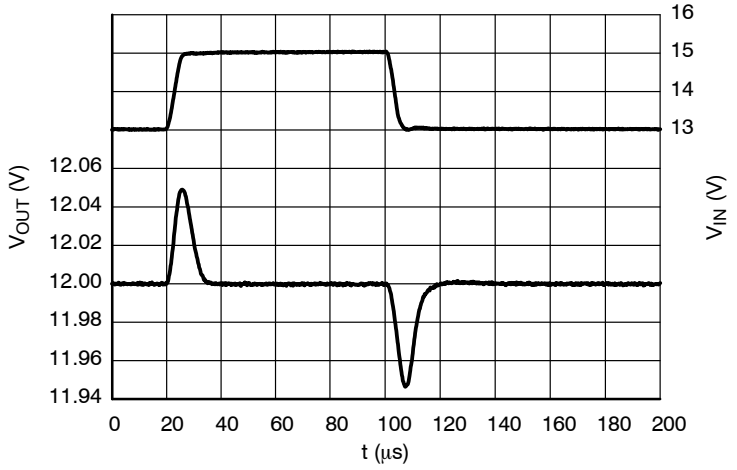


Figure 32. Line Transient Response, V_{OUT} = 12 V

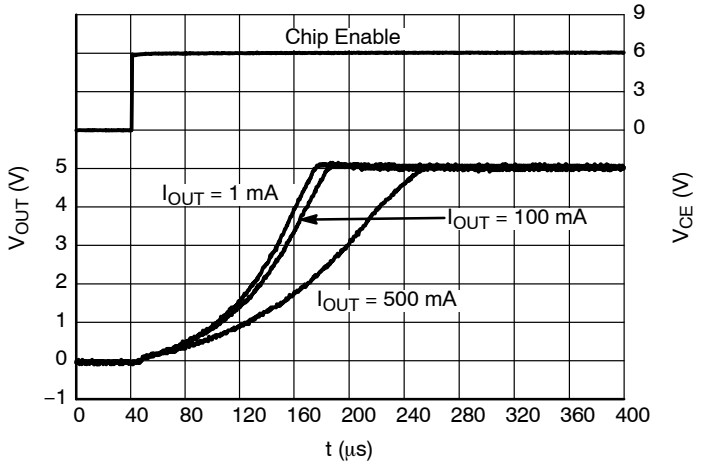


Figure 33. Turn−on Behavior with CE, V_{OUT} = 5 V

TYPICAL CHARACTERISTICS

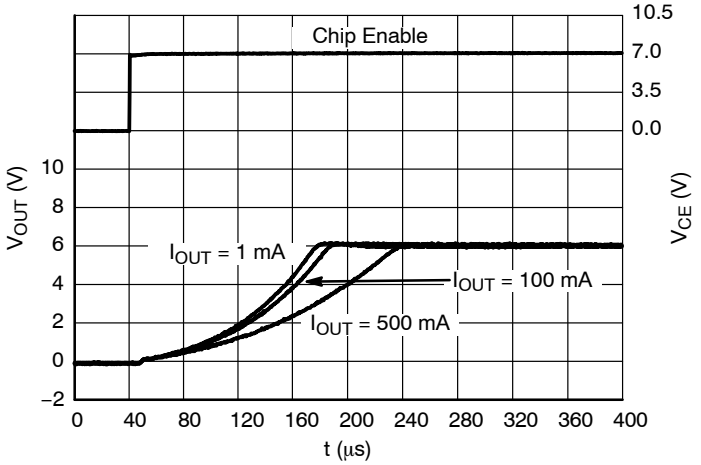


Figure 34. Turn−on Behavior with CE, V_{OUT} = 6 V

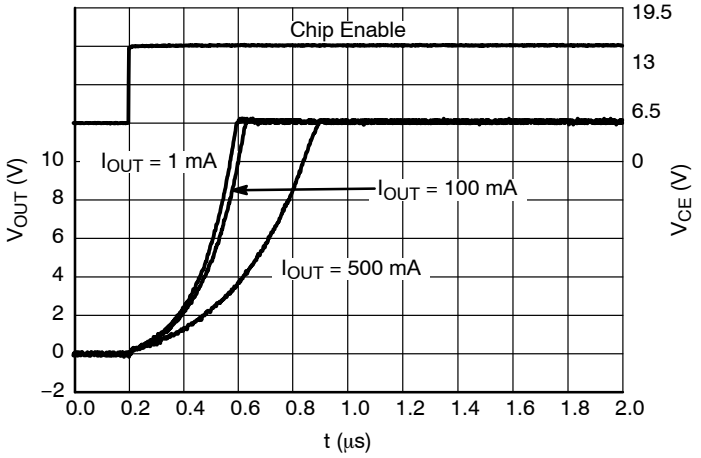


Figure 35. Turn−on Behavior with CE, V_{OUT} = 12 V

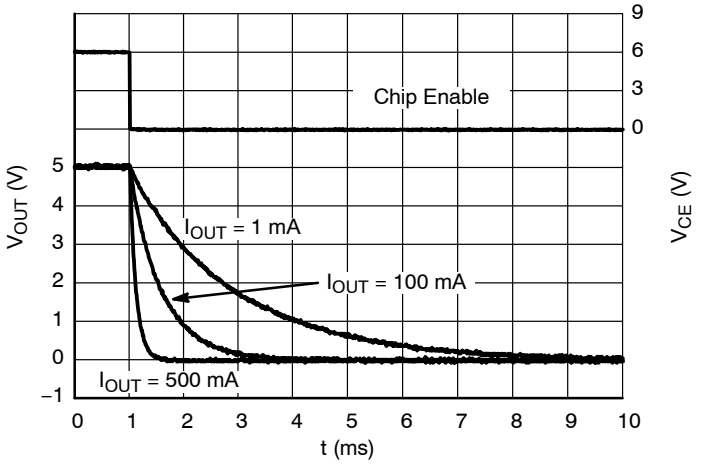


Figure 36. Turn−off Behavior with CE, V_{OUT} = 5 V

TYPICAL CHARACTERISTICS

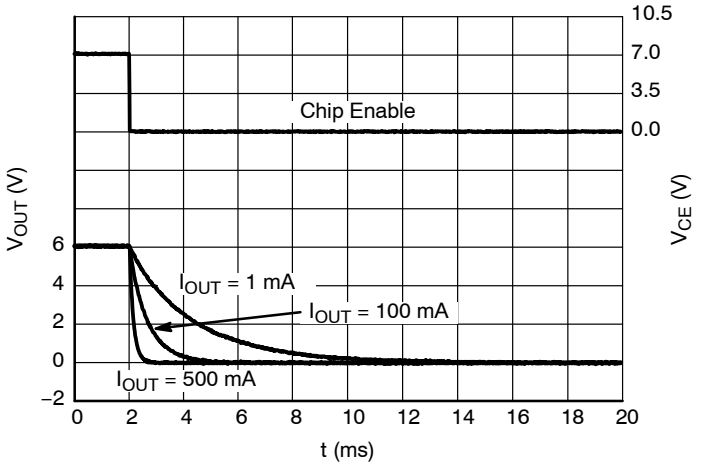


Figure 37. Turn−off Behavior with CE, V_{OUT} = 6 V

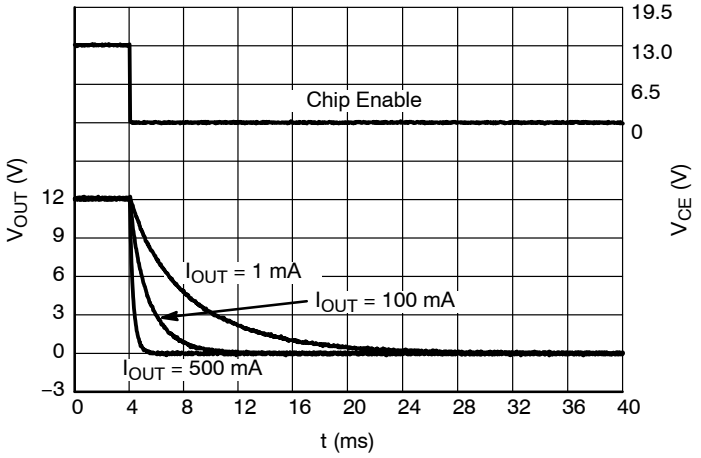


Figure 38. Turn−off Behavior with CE, V_{OUT} = 12 V

APPLICATION INFORMATION

A typical application circuit for NCP4629 series is shown in Figure 39.

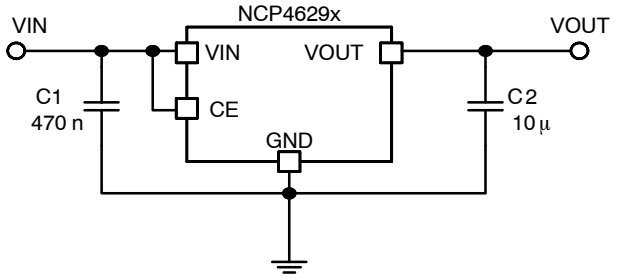


Figure 39. Typical Application Schematic

When VOUT voltage could be higher than VIN voltage it is necessary to use protective diode D1. If there is possibility that VOUT voltage could be negative then it is necessary to use schottky diode D2. See Figure 40 for details. Do not force the voltage to the VOUT pin.

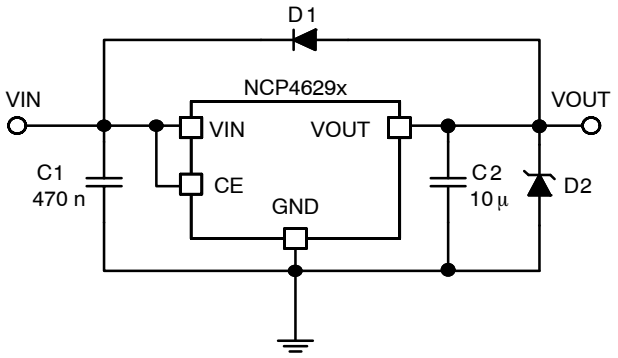


Figure 40. Typical Application Schematic with Protective Diodes

Input Decoupling Capacitor (C1)

A 470 nF ceramic input decoupling capacitor should be connected as close as possible to the input and ground pin of the NCP4629. Higher values and lower ESR improves line transient response.

Output Decoupling Capacitor (C2)

A 10 μF ceramic output decoupling capacitor is sufficient to achieve stable operation of the IC. If tantalum capacitor is used, and its ESR is high, the loop oscillation may result. The capacitor should be connected as close as possible to the output and ground pin. Larger values and lower ESR improves dynamic parameters.

Enable Operation

The enable pin CE may be used for turning the regulator on and off. The IC is switched on when a high level voltage is applied to the CE pin. The enable pin has an internal pull down current source. If the enable function is not needed connect CE pin to VIN.

Thermal

As a power across the IC increase, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature affect the rate of temperature increase for the part. When the device has good thermal conductivity through the PCB the junction temperature will be relatively low in high power dissipation applications.

The IC includes internal thermal shutdown circuit that stops operation of regulator, if junction temperature is higher than 160°C. After that, when junction temperature decreases below 135°C, the operation of voltage regulator would restart. While high power dissipation condition is, the regulator starts and stops repeatedly and protects itself against overheating.

PCB layout

Pins number 2 and 3 must be wired to the GND plane while it is mounted on board. Make VIN and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect capacitors C1 and C2 as close as possible to the IC, and make wiring as short as possible.

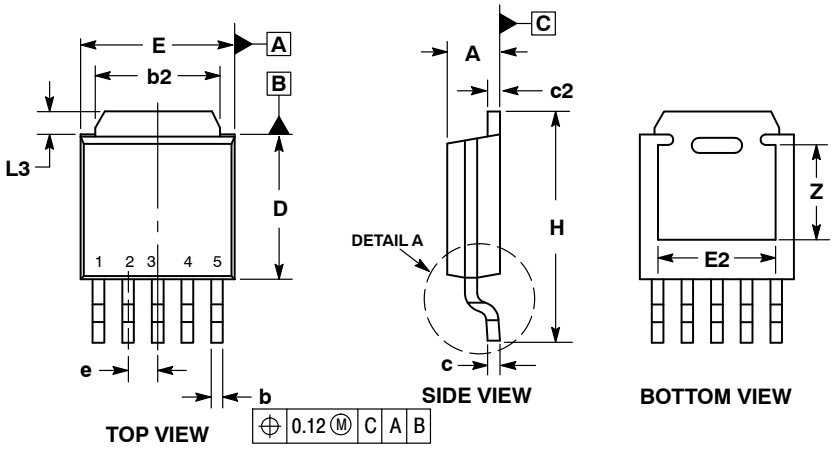
ORDERING INFORMATION

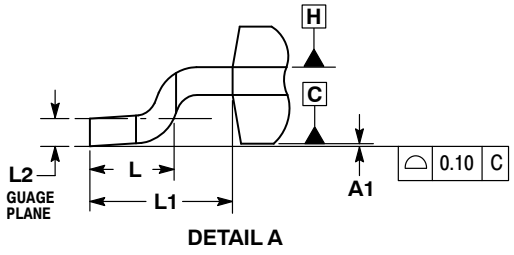
Device	Nominal Output Voltage	Description	Marking	Package	Shipping†
NCP4629HDT050T5G	5.0 V	Enable High	C1J050B	DPACK−5 (Pb−Free)	3000 / Tape & Reel
NCP4629HDT060T5G	6.0 V	Enable High	C1J060B	DPACK−5 (Pb−Free)	3000 / Tape & Reel
NCP4629HDT120T5G	12.0 V	Enable High	C1J120B	DPACK−5 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*To order other package and voltage variants, please contact your ON Semiconductor sales representative.

PACKAGE DIMENSIONS

DPAK−5 (TO−252, 5 LEAD)
CASE 369AE−01
ISSUE O

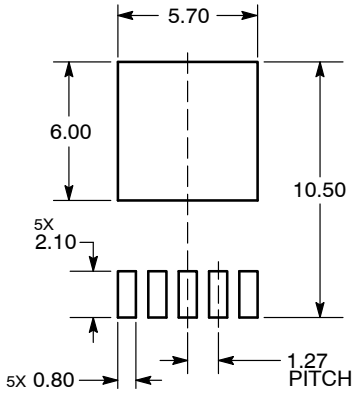




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL, WITHIN DIMENSIONS b3, E2, L3 AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. THESE DIMENSIONS TO BE MEASURED AT DATUM H.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	MILLIMETERS	
DIM	MIN	MAX
A	2.10	2.50
A1	0.00	0.13
b	0.40	0.60
b2	5.14	5.54
c	0.40	0.60
c2	0.40	0.60
D	5.90	6.30
E	6.40	6.80
E2	5.04 REF	
e	1.27 BSC	
H	9.60	10.20
L	1.39	1.78
L1	2.50	2.90
L2	0.51 BSC	
L3	0.90	1.30
Z	2.74 REF	

RECOMMENDED SOLDERING FOOTPRINT*

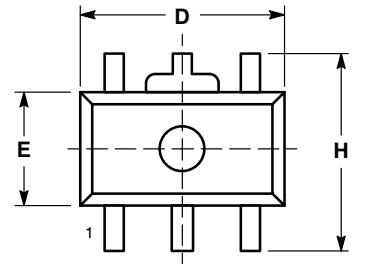


DIMENSIONS: MILLIMETERS

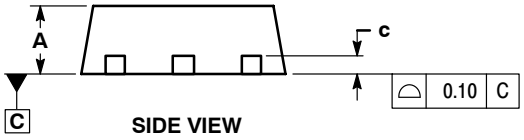
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

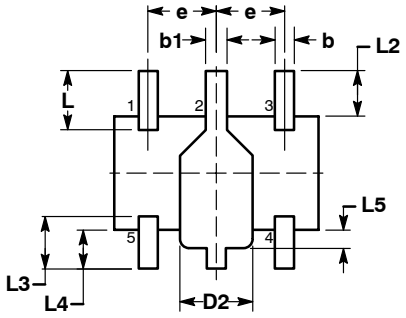
SOT−89, 5 LEAD
CASE 528AB−01
ISSUE O



TOP VIEW



SIDE VIEW

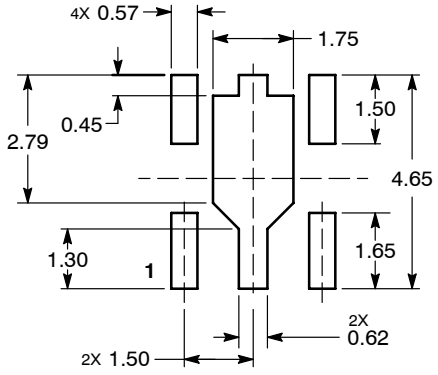


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. DIMENSIONS L, L2, L3, L4, L5, AND H ARE MEASURED AT DATUM PLANE C.

	MILLIMETERS	
DIM	MIN	MAX
A	1.40	1.60
b	0.32	0.52
b1	0.37	0.57
c	0.30	0.50
D	4.40	4.60
D2	1.40	1.80
E	2.40	2.60
e	1.40	1.60
H	4.25	4.45
L	1.10	1.50
L2	0.80	1.20
L3	0.95	1.35
L4	0.65	1.05
L5	0.20	0.60

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

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